

steps as Embodiment 1 of this invention;

OC  
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Fig. <sup>13</sup>~~14~~<sub>1</sub> is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;

Fig. 14 is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;

Fig. 15 is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;

Fig. 16 is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;

Fig. 17 is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;

Fig. 18 is a cross sectional view for a main portion of a semiconductor substrate which shows an example of a method of fabricating a semiconductor device in the order of steps as Embodiment 1 of this invention;